

**PRODUCT / PROCESS CHANGE INFORMATION**

**1. PCI basic data**

|                      |                                                                                   |                                      |
|----------------------|-----------------------------------------------------------------------------------|--------------------------------------|
| 1.1 Company          |  | STMicroelectronics International N.V |
| 1.2 PCI No.          | ANALOG MEMS SENSORS/26/16546                                                      |                                      |
| 1.3 Title of PCI     | STWD100 - Product Flavor Fuses Programming Change.                                |                                      |
| 1.4 Product Category | Pls refer to the impacted products list.                                          |                                      |
| 1.5 Issue date       | 2026-09-25                                                                        |                                      |

**2. PCI Team**

|                           |                          |
|---------------------------|--------------------------|
| 2.1 Contact supplier      |                          |
| 2.1.1 Name                | ROBERTSON HEATHER        |
| 2.1.2 Phone               | +1 8475853058            |
| 2.1.3 Email               | heather.robertson@st.com |
| 2.2 Change responsibility |                          |
| 2.2.1 Product Manager     | Francesco MACINA         |
| 2.1.2 Marketing Manager   | Lionel GRILLO            |
| 2.1.3 Quality Manager     | David MOCELLIN           |

**3. Change**

|                          |                                                                                                                        |                                                                                                                 |
|--------------------------|------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------------------------------------|
| 3.1 Category             | 3.2 Type of change                                                                                                     | 3.3 Manufacturing Location                                                                                      |
| General Product & Design | Die redesign : Mask or mask set change with new die design like metallization (specifically chip frontside) or bug fix | FE: ST Ang Mo Kio SINGAPORE<br>EWS: ST Toa Payo SINGAPORE<br>ASSY: CARSEM M. MALAYSIA<br>FT: CARSEM S. MALAYSIA |

**4. Description of change**

|                                                                                       |                                                                                                                                       |                                  |
|---------------------------------------------------------------------------------------|---------------------------------------------------------------------------------------------------------------------------------------|----------------------------------|
|                                                                                       | Old                                                                                                                                   | New                              |
| 4.1 Description                                                                       | Fuses blown by laser for programming product flavors                                                                                  | Hard coded fuses product flavors |
| 4.2 Anticipated Impact on form,fit, function, quality, reliability or processability? | No Impact on safety or compliance with regulations and fit, function, performance, requirements, or subsequent processing of product. |                                  |

**5. Reason / motivation for change**

|                      |                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                |
|----------------------|------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 5.1 Motivation       | Physical fuses on die are used to program product flavor.<br>These fuses are blown by laser for programming product flavor (P: tWD = 3.4ms/tPW = 3.4ms, W: tWD = 6.3ms/tPW = 210ms, X: tWD = 102ms/tPW = 210ms, Y: tWD = 1.6s/tPW = 210ms).<br>Fuses abnormality was found in production after detecting yield loss at Electrical Wafer Sorting tests in place.<br>Flavor fuses mask will be modified, hard coding product flavor fuses.<br>Flavor fuses will not be blown anymore.<br>Unit Level Traceability fuses are still blown by laser. |
| 5.2 Customer Benefit | QUALITY IMPROVEMENT                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                                            |

**6. Marking of parts / traceability of change**

|                 |                       |
|-----------------|-----------------------|
| 6.1 Description | Internal codification |
|-----------------|-----------------------|

**7. Timing / schedule**

|                                     |                |
|-------------------------------------|----------------|
| 7.1 Date of qualification results   | 2026-06-26     |
| 7.2 Intended start of delivery      | 2026-10-25     |
| 7.3 Qualification sample available? | Not Applicable |

**8. Qualification / Validation**

|                                                    |                                                         |            |            |
|----------------------------------------------------|---------------------------------------------------------|------------|------------|
| 8.1 Description                                    | 16546 STWD100_FUSE_PRGM_CHANGE_Results Presentation.pdf |            |            |
| 8.2 Qualification report and qualification results | Available (see attachment)                              | Issue Date | 2026-09-25 |

| 9. Attachments (additional documentations)                                          |  |  |
|-------------------------------------------------------------------------------------|--|--|
| 16546 Public product.pdf<br>16546 STWD100_FUSE_PRGM_CHANGE_Results Presentation.pdf |  |  |

| 10. Affected parts      |                         |                          |
|-------------------------|-------------------------|--------------------------|
| 10. 1 Current           |                         | 10.2 New (if applicable) |
| 10.1.1 Customer Part No | 10.1.2 Supplier Part No | 10.1.2 Supplier Part No  |
|                         | STWD100NWWY3F           |                          |
|                         | STWD100NXWY3F           |                          |
|                         | STWD100NYWY3F           |                          |
|                         | STWD100YNWWY3F          |                          |
|                         | STWD100YNXWY3F          |                          |
|                         | STWD100YNYWY3F          |                          |

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